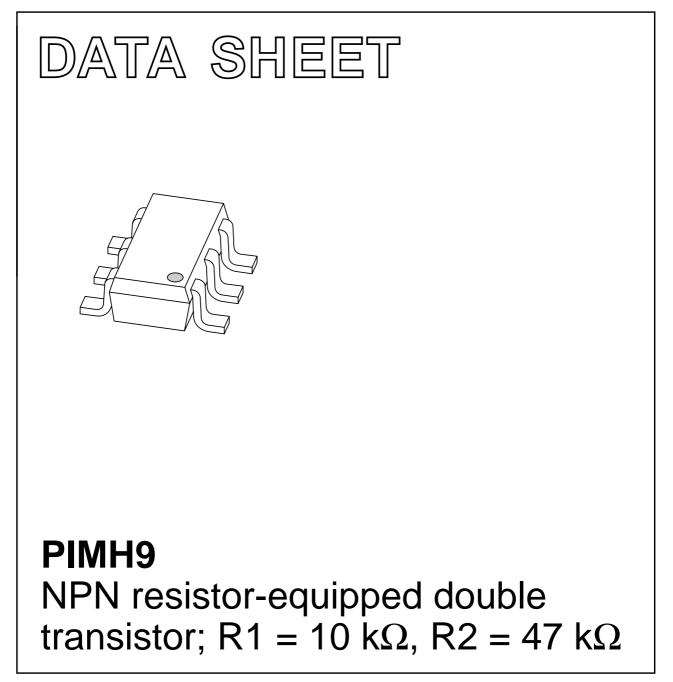
DISCRETE SEMICONDUCTORS



Product specification

2001 Sep 13



PIMH9

FEATURES

- Transistors with built-in bias resistors (R1 typ. 10 k Ω and R2 typ. 47 k $\Omega)$
- No mutual interference between the transistors
- Simplification of circuit design
- Reduces number of components and board space.

APPLICATIONS

- General purpose switching and amplification
- Inverter and interface circuits
- Circuit driver.

DESCRIPTION

NPN resistor-equipped double transistor in an SC-74 (SOT457) plastic package.

MARKING

TYPE NUMBER	MARKING CODE			
PIMH9	H9			

PINNING

PIN		DESCRIPTION
1, 4	emitter	TR1; TR2
2, 5	base	TR1; TR2
6, 3	collector	TR1; TR2

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT	
V _{CEO}	collector-emitter voltage	50	V	
I _{CM}	peak collector current	100	mA	
R1	bias resistor	10	kΩ	
R2	bias resistor	47	kΩ	

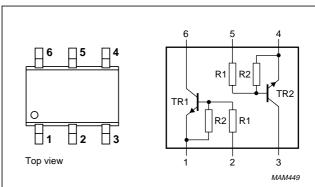


Fig.1 Simplified outline (SC-74; SOT457) and symbol.

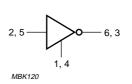


Fig.2 Equivalent inverter symbol.

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per transist	tor				•
V _{CBO}	collector-base voltage	open emitter	-	50	V
V _{CEO}	collector-emitter voltage	open base	_	50	V
V _{EBO}	emitter-base voltage	open collector	_	10	V
VI	input voltage				
	positive		_	+40	V
	negative		_	-10	V
lo	output current (DC)		_	100	mA
I _{CM}	peak collector current		_	100	mA
P _{tot}	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$; note 1	_	300	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C
Per device					
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	600	mW

Note

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm².

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT	
R _{th j-a}	thermal resistance from junction to ambient	note 1	208	K/W	

Note

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm².

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CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

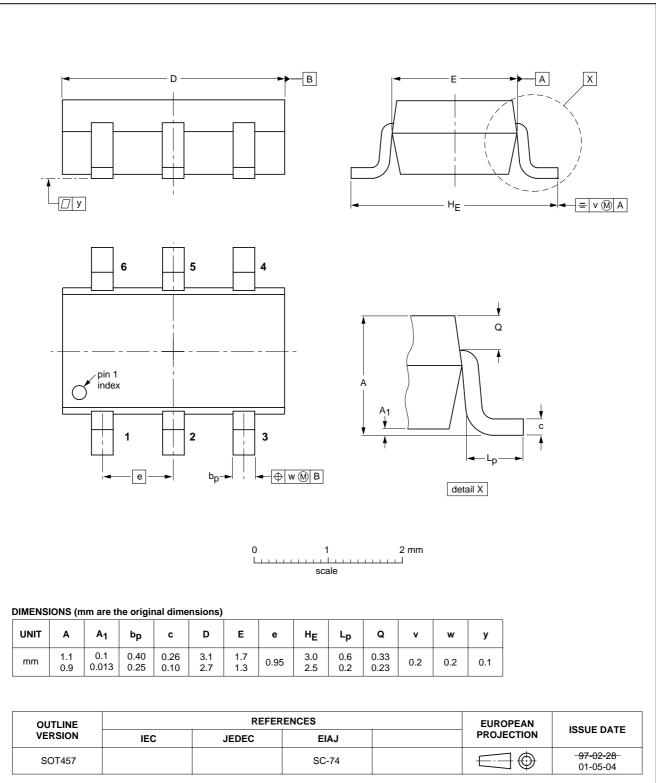
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Per transist	Per transistor					
I _{CBO}	collector-base cut-off current	$V_{CB} = 50 \text{ V}; \text{ I}_{\text{E}} = 0$	_	-	100	nA
I _{CEO}	collector-emitter cut-off current	$V_{CE} = 50 \text{ V}; \text{ I}_{B} = 0$	-	-	1	μA
		$V_{CE} = 30 \text{ V}; \text{ I}_{B} = 0; \text{ T}_{j} = 150 ^{\circ}\text{C}$	-	-	50	μA
I _{EBO}	emitter-base cut-off current	$V_{EB} = 5 \text{ V}; \text{ I}_{C} = 0$	-	-	150	μA
h _{FE}	DC current gain	$V_{CE} = 5 \text{ V}; I_{C} = 5 \text{ mA}$	100	-	_	
V _{CEsat}	saturation voltage	I _C = 5 mA; I _B = 0.25 mA	-	-	100	mV
V _{i(off)}	input off voltage	$V_{CE} = 5 \text{ V}; \text{ I}_{C} = 100 \mu\text{A}$	-	0.7	0.5	V
V _{i(on)}	input on voltage	V _{CE} = 0.3 V; I _C = 1 mA	1.4	0.8	_	V
R ₁	input resistor		7	10	13	kΩ
R2	resistor ratio		3.7	4.7	5.7	
R1						
C _c	collector capacitance	$I_{E} = i_{e} = 0; V_{CB} = 10 V;$ f = 1 MHz	-	-	2.5	pF

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NPN resistor-equipped double transistor; R1 = 10 k Ω , R2 = 47 k Ω

PACKAGE OUTLINE

Plastic surface mounted package; 6 leads



SOT457

PIMH9

DATA SHEET STATUS

DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITIONS
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